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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Yeo, et al.

Serial No.: 10/078,718

Filed: February 19, 2002

For: **Enhanced Chip Scale Package
For Wire Bond Dies**

Attorney's Docket No. 4795-002

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Thai, Luan C.
Examiner
Group Art Unit: 2827

Raleigh, North Carolina

April 11, 2003

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

RESPONSE TO NON-FINAL OFFICE ACTION MAILED JANUARY 14, 2003

Dear Sir:

Applicants submit the following response in reply to the Office Action mailed on the above date. The Commissioner is hereby authorized to charge any fees or charges due in association with this response to Deposit Account 18-1167.